



Winner of the  
**productronica**  
innovation award 2019

## Future Markets cluster – F&S BONDTEC Semiconductor



### **BAMFIT Tester**

BAMFIT (Bond Accelerated Mechanical Fatigue Interconnect Test) is a disruptive and innovative method for carrying out extremely accelerated and fully automated reliability and service life tests on heavy wire bonds in power semiconductors. The BAMFIT Tester takes classic power cycling to the next level by means of an automated rapid test which lasts just a few minutes whereas power cycling tests used to date can take up to several months. The

BAMFIT Tester also means that semi-quantitative reliability and service life tests can be carried out as part of the development and manufacturing processes, thus swiftly providing answers to questions on, for example, the effects of material and process changes. The BAMFIT Tester was created based on an automatic wire bonder and has a patent pending.



### **Siegfried Seidl, MAS, Managing Partner, F&S BONDTEC:**

“We are absolutely thrilled to receive the productronica Innovation Award 2019. It is recognition of our extremely successful collaboration with TU Wien (Vienna University of Technology) on reliability diagnostics for power electronics: our revolutionary BAMFIT Tester is almost like a ‘time machine’ as it reduces the classic service life tests for heavy wire bonds from months down to minutes and thus significantly expands the range of diagnostic possibilities. This is a huge advantage, especially in the e-mobility era in which power electronics are becoming increasingly important.”

### **F&S BONDTEC Semiconductor GmbH, Braunau am Inn, Austria**

F&S BONDTEC is a global technology leader in the field of semi-automatic and fully automatic devices for wire bonding and testing. Since it was founded 25 years ago, the company has increased its number of employees from 5 to 40 and its success has always been due to its consistent focus on devices that offer maximum flexibility and are extremely easy to use and are therefore top-quality end products. The automatic processes even with the entry-level devices ensure that the quality of the bonding and testing is never dependent on the operator. The fact that the machines can be converted and therefore switch between bonding and testing procedures ensures they are a sound investment for users. The real recipe for success though can be found in the machines’ software which sets new standards on the global market in terms of user-friendliness, overall performance and flexibility. Well over a thousand installed machines with several thousand bond heads and measuring heads on the entire global market are impressive proof of this.

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